



Please note that Cypress is an Infineon Technologies Company.

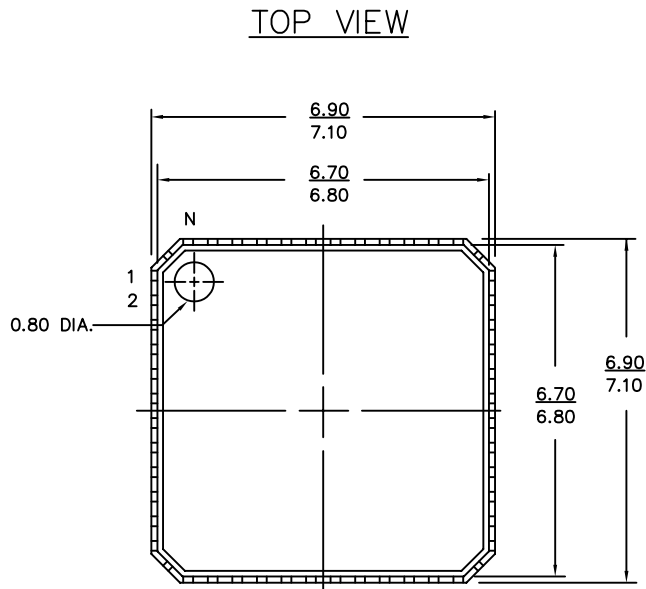
The document following this cover page is marked as “Cypress” document as this is the company that originally developed the product. Please note that Infineon will continue to offer the product to new and existing customers as part of the Infineon product portfolio.

Continuity of document content

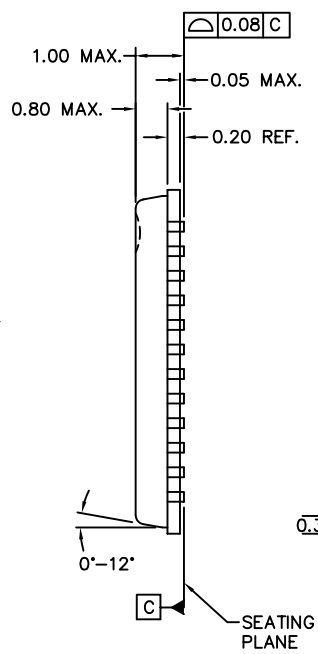
The fact that Infineon offers the following product as part of the Infineon product portfolio does not lead to any changes to this document. Future revisions will occur when appropriate, and any changes will be set out on the document history page.

Continuity of ordering part numbers

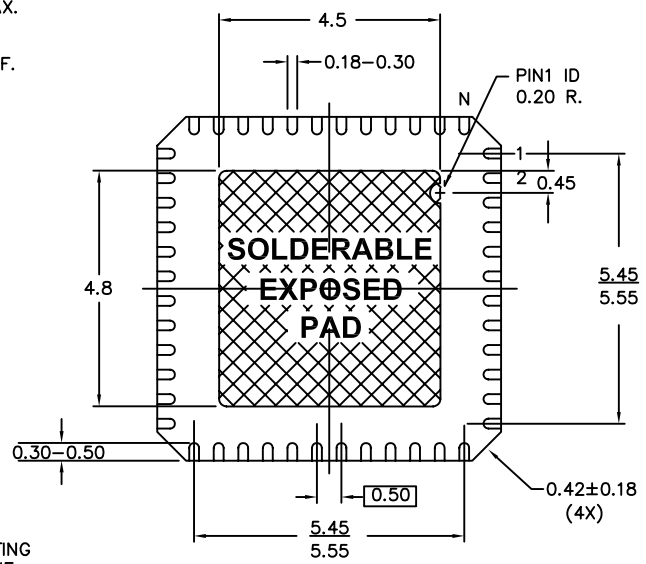
Infineon continues to support existing part numbers. Please continue to use the ordering part numbers listed in the datasheet for ordering.



SIDE VIEW



BOTTOM VIEW



NOTES:

1. HATCH AREA IS SOLDERABLE EXPOSED METAL.
2. REFERENCE JEDEC#: MO-220
3. PACKAGE WEIGHT: 0.13g
4. ALL DIMENSIONS ARE IN MM [MIN/MAX]
5. PACKAGE CODE


PART #	DESCRIPTION
LF48	STANDARD
LY48	LEAD FREE

CYPRESS Company Confidential	
TITLE PACKAGE OUTLINE, 48LD QFN 7X7X1.0 MM LF48/LY48 4.5X4.8 EPAD (SUBCON PUNCH TYPE)	
SPEC NO. 51-85152	REV *G
SCALE	SHEET 1 OF 2

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PACKAGE CODE(S) LF48 LY48

REVISIONS						
PAGE	ZONE	REV	ECN	DESCRIPTION	DATE	APPROVED
ALL	-	**	111397	NEW RELEASE	11/05/01	N/A
ALL	-	*A	4584955	REMOVE DETAIL MARK AT 4 CORNERS BTM VIEW/ CHG. PIN 1 ID AT BTM VIEW.	07/24/02	N/A
ALL	-	*B	212323	ADD E-PAD DIMENSION/ ADD JEDEC#/ ADD PKG. WEIGHT/ CHG. PART #	07/24/02	N/A
ALL	-	*C	736321	REVISED DRAWING, DEFINED SOLDERABLE EXPOSED AREA CHANGED SPEC. TITLE, CORRECTED EPAD DIMENSION	01/29/07	JSO
ALL	-	*D	2813378	48LD QFN 7 X 7mm PACKAGE OUTLINE (SUBCON PUNCH TYPE PKG with 3.8 X 3.8 EPAD) to PACKAGE OUTLINE, 48LD QFN 7X7X1.0 MM LF48/LY48 3.8X3.8 EPAD (SUBCON PUNCH TYPE).	11/23/09	QAD
ALL	-	*E	3159033	NO CHANGE	02/01/11	QAD
ALL	-	*F	3378059	EPAD changed from 3.8x3.8 to 4.5x4.8mm. Title changed as well. Analysis of active products showed only data sheet 38-16017 called out this package outline. Actual product and assembly house drawing confirmed actual EPAD size to be 4.5x4.8mm. Lead width and length dimension adjusted to meet supplier drawing.	09/20/11	MLA
ALL	-	*G	4584955	Sunset Review, Changed drawing template.	12/02/14	QAD

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SPEC NO. 51-85152	REV *G
SCALE	SHEET 2 OF 2

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